TOSHIBA Injection Enhanced Gate Transistor Silicon N Channel IEGT

# GT40Q321

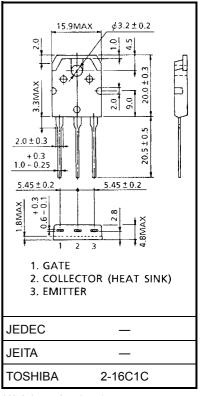
# Voltage Resonance Inverter Switching Application

Unit: mm

- The 5th generation
- Enhancement-mode
- High speed :  $t_f = 0.41 \mu s$  (typ.) (IC = 40A)
- Low saturation voltage:  $V_{CE (sat)} = 2.8 \text{ V (typ.)} (I_C = 40\text{A})$
- FRD included between emitter and collector

## **Maximum Ratings (Ta = 25°C)**

Characteristics		Symbol	Rating	Unit	
Collector-emitter voltage		$V_{CES}$	1200	V	
Gate-emitter voltage		$V_{GES}$	±25	V	
Continuous collector current	@ Tc = 100°C	Ic	23	Α	
	@ Tc = 25°C	iC	42		
Pulsed collector current		I <sub>CP</sub>	80	Α	
Diode forward current	DC	I <sub>F</sub>	10	Α	
	Pulsed	I <sub>FP</sub>	80		
Collector power dissipation	@ Tc = 100°C	Pc	68	W	
	@ Tc = 25°C	ьС	170	W	
Junction temperature		Tj	150	°C	
Storage temperature range		T <sub>stg</sub>	−55 to 150	°C	

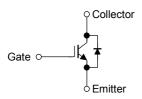


Weight: 4.6 g (typ.)

### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance (IGBT)	R <sub>th (j-c)</sub>	0.74	°C/W
Thermal resistance (diode)	R <sub>th (j-c)</sub>	1.79	°C/W

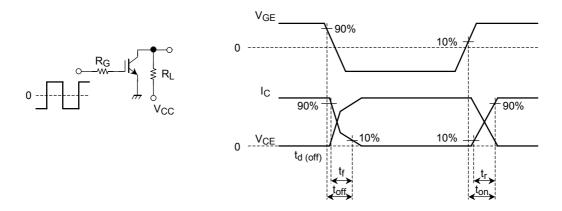
# **Equivalent Circuit**



## **Electrical Characteristics (Ta = 25°C)**

Chara	acteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cur	rent	I <sub>GES</sub>	V <sub>GE</sub> = ±25 V, V <sub>CE</sub> = 0	_	_	±500	nA
Collector cut-off of	current	I <sub>CES</sub>	V <sub>CE</sub> = 1200 V, V <sub>GE</sub> = 0	_	_	5.0	mA
Gate-emitter cut-	off voltage	V <sub>GE</sub> (OFF)	$I_C$ = 40 mA, $V_{CE}$ = 5 V	4.0	_	7.0	V
Collector-emitter saturation voltage		V <sub>CE</sub> (sat)	I <sub>C</sub> = 40 A, V <sub>GE</sub> = 15 V	_	2.8	3.6	V
Input capacitance		C <sub>ies</sub>	V <sub>CE</sub> = 10 V, V <sub>GE</sub> = 0, f = 1 MHz	_	3200	_	pF
Switching time	Rise time	t <sub>r</sub>	Resistive Load	_	0.19	_	μs
	Turn-on time	t <sub>on</sub>	V <sub>CC</sub> = 600 V, I <sub>C</sub> = 40 A	_	0.25	_	
	Fall time	t <sub>f</sub>	$V_{GG}$ = ±15 V, $R_{G}$ = 39 $\Omega$	_	0.41	0.72	
	Turn-off time	t <sub>off</sub>	(Note 1)	_	0.57	_	
Diode forward voltage V <sub>F</sub>		V <sub>F</sub>	I <sub>F</sub> = 10 A, V <sub>GE</sub> = 0	_	_	2.0	V
Reverse recovery time t		t <sub>rr</sub>	I <sub>F</sub> = 10 A, di/dt = -20 A/μs	_	0.6	_	μs

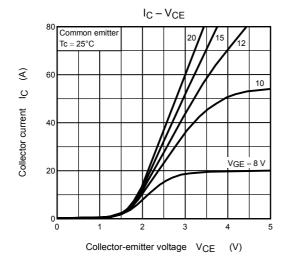
Note 1: Switching time measurement circuit and input/output waveforms

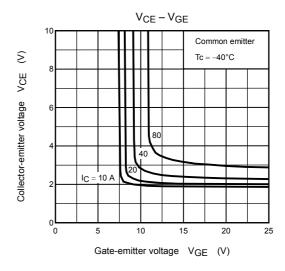


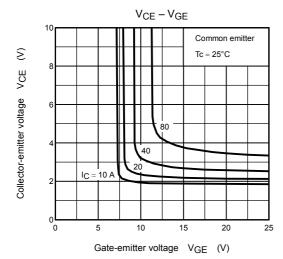
#### **General Safety Precautions and Usage Considerations**

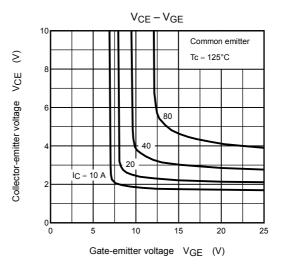
- The GT40Q321 is only intended for single-transistor voltage resonant circuits in induction heating (IH) equipment. For other applications, please contact your nearest Toshiba sales office.
- Do not use devices under conditions in which their maximum ratings will be exceeded. A device may break down or its performance may be degraded, causing it to catch fire or explode resulting in injury to the user. It is therefore necessary to incorporate device derating into circuit design.
- In all IGBT devices, maximum collector-emitter voltage (VCES) decreases when the junction temperature becomes low. It is therefore necessary to incorporate device derating into circuit design.
- Maximum collector current is calculated from Tj MAX.(150°C), the thermal resistance and DC forward power dissipation. However it's limited in real application by another factors such as switching loss, limitation of the inner bonding wires and so on.

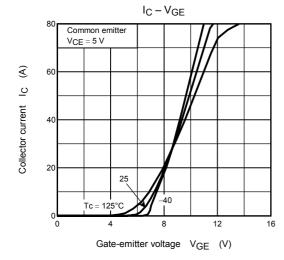
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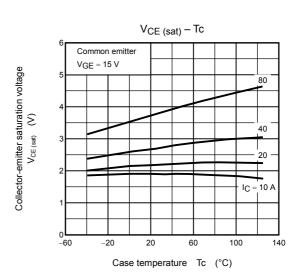


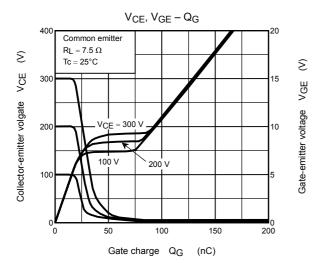


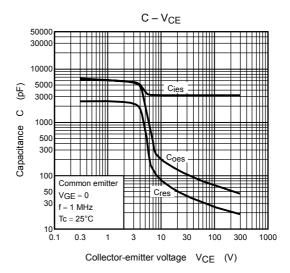


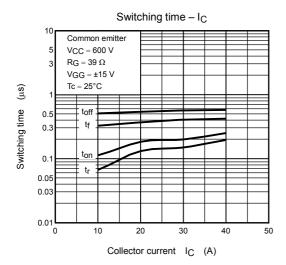


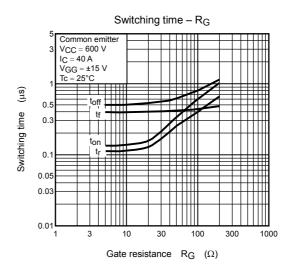


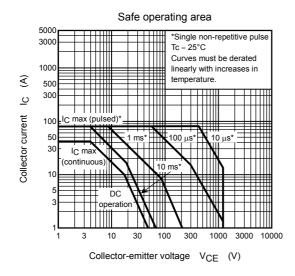


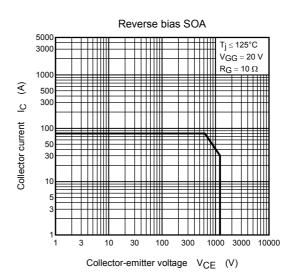




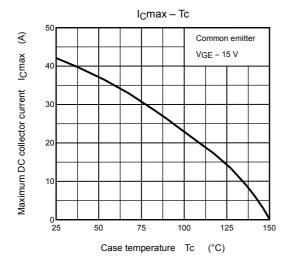


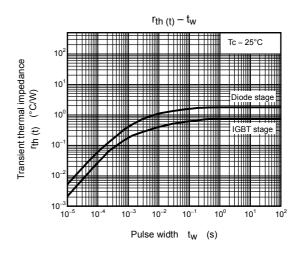


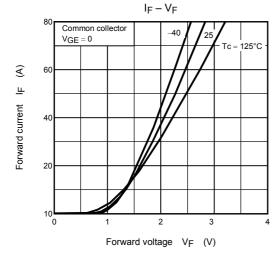


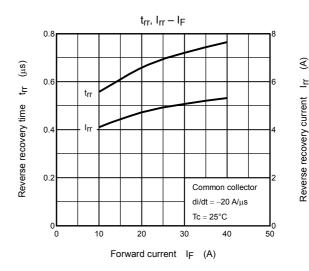


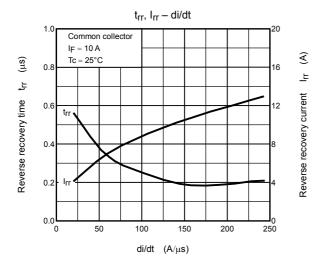
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